GE Energy	**Functional Testing Specification**
Parts & Repair Services ***Louisville, KY***	**LOU-GENEVA-IS200EDEX**

Test Procedure for an IS200EDEX card tested on the GENEVA Test System

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	R. Duvall	05/21/03
B	Transferred procedure from a general group to a specific single document and added asset numbers to section 5. **Also added special note concerning TIL 1862 to step 6.1.1.**	C. Wade	10/23/2012
B			
C			

PREPARED BY	REVIEWED BY	REVIEWED BY	QUALITY APPROVAL
Robert Duvall	C. Wade		Robert Duvall
DATE	**DATE**	**DATE**	**DATE**
05/21/03	10/23/2012		05/21/03

Functional test procedure for equipment tested on the GENRAD® GENEVA system

1. SCOPE

1.1 This is a functional testing procedure for IS200EDEXG1B circuit boards.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
3.1.1 Check the board's electronic folder for more information.

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning
4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.
4.2 Equipment Inspection
4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
4.2.1.1 Wires broken or cracked
4.2.1.2 Terminal strips / connectors broken or cracked
4.2.1.3 Loose wires
4.2.1.4 Components visually damaged
4.2.1.5 Capacitors leaking
4.2.1.6 Solder joints damaged or cold
4.2.1.7 Circuit board burned or de-laminated
4.2.1.8 Printed wire runs burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1	H188912	GENRAD Geneva Test System
1	H188756	Geneva Test Fixture EDEX #40

6. Testing Process

6.1 Setup

6.1.1 **Technical Information Letter 1862 must be followed. It covers installing two small capacitors to filter out un-wanted noise. See picture in section 8. This must be done on all IS200EDEXG1BAA cards. MCS is selling this upgrade on all IS200EDEXG1BAA cards**

6.1.2 Install fixture H188756 onto Geneva test System.

6.1.3 Install UUT into test fixture.

6.2 Testing Procedure

6.2.1 Load appropriate test program and follow instructions on screen.

6.3 ***TEST COMPLETE ***

7. Notes

7.1 Changes to the electronic test file are located in the following directory on the local hard drive; C:\GenevaInfo\Geneva\Geneva Test Fixture Notes.

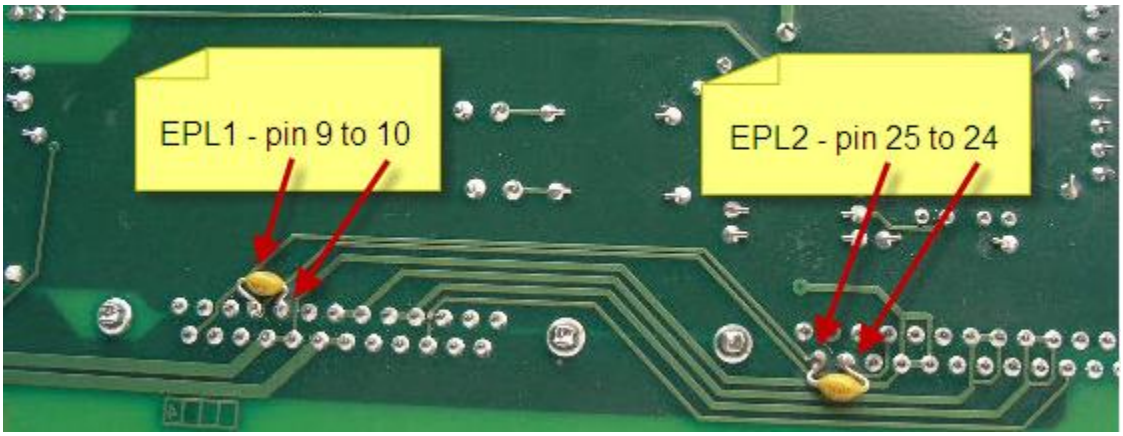
7.1.1 These changes have been backed up on CD.

8. Attachments

8.1 Picture of the Geneva Test System

8.2 ECN for IS200EDEXG1BAA to IS200EDEXG1BBA

8.2.1 Add qty 2 of 104X122AA__399 (0.1uF, 50V) capacitor. Connect one from net STATUS1 (Pin-10) to COMA (Pin-9 or Pin-8), and the other from STATUS2 (Pin-25) to COMB (Pin-24 or Pin-23). As a cobble, this can be done by soldering the capacitors on the bottom side of the board at connector EPL2. Connect one between pins 8 and 10, and the other between pins 23 and 25.



Picture on ECN properly completed